
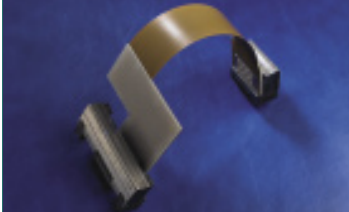

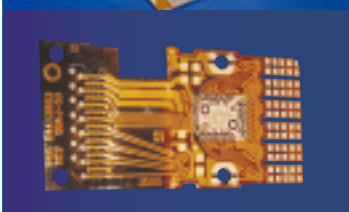




Molex Flexible Printed Circuit Technology is the answer to your most challenging interconnect applications. We are your total solution for Flexible Printed Circuitry because we design and manufacture both the flex and the connectors. A Flexible Printed Circuit (FPC or Flex) is an ultra-reliable technology. An FPC can be the best solution for creating products which are complex, small, lightweight or have harsh environmental conditions. Flex can be designed to meet a wide range of temperature and environmental extremes.

Flex circuits are excellent for designs with high-density circuitry, and are more suited for dynamic applications such as hinge and drawer applications.

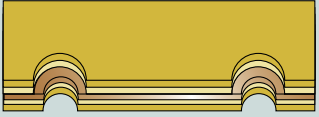
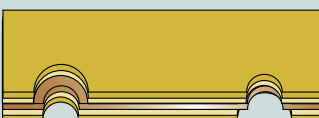

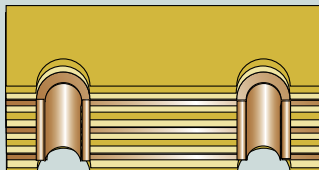
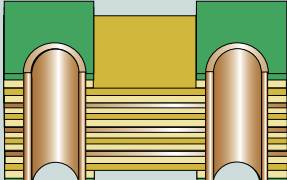
Most commonly, flex acts as an interconnect device. Flex circuits make electronic interconnection both simpler and more reliable. FPC interconnects are often used in applications where high signal speed, heat, flexibility, or space savings are issues.

This custom solution has a variety of applications. An FPC can replace a traditional printed circuit board.

	Product	Features	Flex Construction	Standard Interconnects
	<b>High Speed Rigid Flex</b>	<ul style="list-style-type: none"> <li>■ Surface mount on both sides</li> <li>■ Stronger barrels</li> <li>■ Press-fit connector capability</li> </ul>	<ul style="list-style-type: none"> <li>■ Rigid flex</li> </ul>	Plateau HS Mezz™, SlimStack™, 0.50mm (.020") stacking systems, VHDM®
	<b>High Speed Flex Assemblies</b>	<ul style="list-style-type: none"> <li>■ Typically 3 or more layers</li> <li>■ Large number of interconnect options</li> <li>■ High conductive routing area</li> </ul>	<ul style="list-style-type: none"> <li>■ Multi-layer</li> </ul>	Plateau HS Mezz, SlimStack, 0.50mm (.020") stacking systems, VHDM, C-Grid®, Milli-Grid™, EBBI™
	<b>Flex Backplanes</b>	<ul style="list-style-type: none"> <li>■ High signal frequency</li> <li>■ Controlled impedance</li> <li>■ Improves airflow within the system</li> </ul>	<ul style="list-style-type: none"> <li>■ Multi-layer</li> <li>■ Rigid flex</li> </ul>	VHDM, VHDM-HSD™, MZP™, PCI Express, SATA, SAS, MFB™, Omnigrd®
	<b>High Density Flex</b>	<ul style="list-style-type: none"> <li>■ Typically 2 or more layers</li> <li>■ Tight line and space widths</li> <li>■ Reduces weight</li> <li>■ Better thermal characteristics than standard rigid board constructions</li> </ul>	<ul style="list-style-type: none"> <li>■ Double sided</li> <li>■ Multi-layer</li> </ul>	C-Grid, Milli-Grid, SlimStack, 1.00 to .030mm (.039 to .012") board-to-board systems
	<b>Flex Interconnect Assemblies</b>	<ul style="list-style-type: none"> <li>■ Virtually unlimited variety of interconnect options</li> <li>■ Reduces assembly time</li> <li>■ Excellent thermal management</li> </ul>	<ul style="list-style-type: none"> <li>■ Single sided</li> <li>■ Single sided dual access</li> <li>■ Double sided</li> <li>■ Multi-layer</li> </ul>	C-Grid, Milli-Grid, SlimStack, 1.00 to .030mm (.039 to .012") board-to-board systems, MicroCross™ DVI, RJ-11, RJ-45, Mini-Fit®, Micro-Fit 3.0™, EBBI™, CradleCon™, LFH™, HDMI, USB
	<b>Flex Jumpers</b>	<ul style="list-style-type: none"> <li>■ Eliminates wire harnesses</li> <li>■ Reduces package size</li> <li>■ At least one ZIF end connection</li> </ul>	<ul style="list-style-type: none"> <li>■ Single sided</li> <li>■ Single sided dual access</li> <li>■ Double sided</li> </ul>	1.27 to 0.50mm (.050 to .020") ZIF systems

\* VHDM-HSD is a trademark of Amphenol, Corp.

† VHDM is a trademark or registered trademark of Amphenol, Corp.

	Flex Construction	Description	Applications
	<b>Single Sided</b>	<ul style="list-style-type: none"> <li>■ One conductive layer</li> </ul>	<ul style="list-style-type: none"> <li>■ Jumpers (board-to-board interconnect)</li> <li>■ Print head cables</li> <li>■ Wire harness replacements</li> <li>■ Power control modulators</li> <li>■ Low cost jumpers</li> </ul>
	<b>S2 - Single Sided Dual Access</b>	<ul style="list-style-type: none"> <li>■ One conductive layer, access from both sides</li> </ul>	<ul style="list-style-type: none"> <li>■ Jumpers (board-to-board interconnect)</li> <li>■ Disk drives</li> <li>■ Consumer electronics</li> <li>■ Automotive controls and sensors</li> </ul>
	<b>Double Sided</b>	<ul style="list-style-type: none"> <li>■ Two conductive layers</li> </ul>	<ul style="list-style-type: none"> <li>■ Digital displays for consumer and hand-held items</li> <li>■ Industrial electronic controls</li> <li>■ LED panels for military and medical devices</li> <li>■ Digital cameras</li> </ul>
	<b>Multi-Layer</b>	<ul style="list-style-type: none"> <li>■ More than two conductive layers</li> </ul>	<ul style="list-style-type: none"> <li>■ Servers and high-end computers</li> <li>■ Laptop computers</li> <li>■ Computer storage</li> <li>■ Telecom base stations, hubs and routers</li> <li>■ Mobile phones</li> </ul>
	<b>Rigid Flex</b>	<ul style="list-style-type: none"> <li>■ Combination of traditional PCB and Flex created into one continuous piece</li> </ul>	<ul style="list-style-type: none"> <li>■ Military electronics</li> <li>■ Flex applications requiring SMT components on both sides</li> <li>■ Flex applications that need press-fit connectors</li> <li>■ Mobile medical equipment</li> <li>■ High temperature and harsh environment applications</li> </ul>